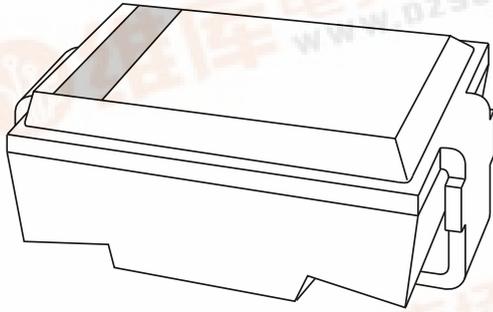


**DISCRETE SEMICONDUCTORS**

# DATA SHEET



## **BYG60 series** Fast soft-recovery controlled avalanche rectifiers

Preliminary specification  
File under Discrete Semiconductors, SC01

1996 Jun 05

# Fast soft-recovery controlled avalanche rectifiers

## BYG60 series

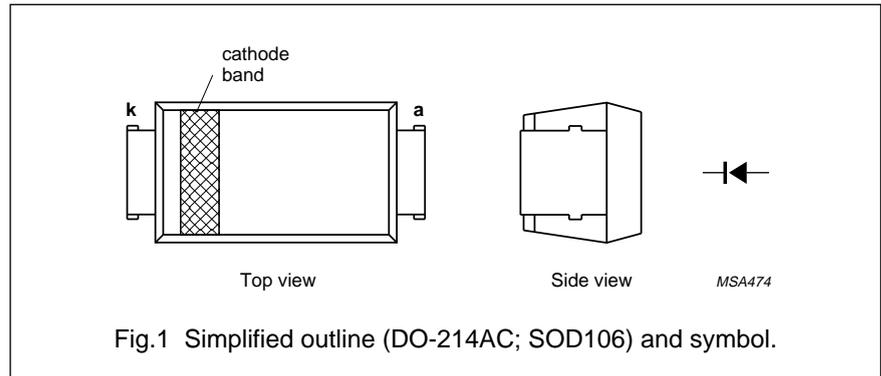
**FEATURES**

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- UL 94V-O classified plastic package
- Shipped in 12 mm embossed tape.

**DESCRIPTION**

DO-214AC surface mountable package with glass passivated chip.

The well-defined void-free case is of a transfer-moulded thermo-setting plastic.



**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL             | PARAMETER                           | CONDITIONS   | MIN. | MAX. | UNIT |
|--------------------|-------------------------------------|--|------|------|------|
| V <sub>RRM</sub>   | repetitive peak reverse voltage     |  |      |      |      |
|                    | BYG60D                              |  | –    | 200  | V    |
|                    | BYG60G                              |  | –    | 400  | V    |
|                    | BYG60J                              |  | –    | 600  | V    |
|                    | BYG60K                              |  | –    | 800  | V    |
|                    | BYG60M                              |  | –    | 1000 | V    |
| V <sub>R</sub>     | continuous reverse voltage          |  |      |      |      |
|                    | BYG60D                              |  | –    | 200  | V    |
|                    | BYG60G                              |  | –    | 400  | V    |
|                    | BYG60J                              |  | –    | 600  | V    |
|                    | BYG60K                              |  | –    | 800  | V    |
|                    | BYG60M                              |  | –    | 1000 | V    |
| I <sub>F(AV)</sub> | average forward current             | averaged over any 20 ms period;<br>T <sub>tp</sub> = 100 °C; see Fig.2   | –    | 1.90 | A    |
|                    |                                     | averaged over any 20 ms period;<br>Al <sub>2</sub> O <sub>3</sub> PCB mounting (see Fig.7);<br>T <sub>amb</sub> = 60 °C; see Fig.3 | –    | 0.90 | A    |
|                    |                                     | averaged over any 20 ms period;<br>epoxy PCB mounting (see Fig.7);<br>T <sub>amb</sub> = 60 °C; see Fig.3                          | –    | 0.65 | A    |
| I <sub>FSM</sub>   | non-repetitive peak forward current | t = 10 ms half sine wave;<br>T <sub>j</sub> = T <sub>jmax</sub> prior to surge;<br>V <sub>R</sub> = V <sub>RRMmax</sub>            | –    | 25   | A    |

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| SYMBOL    | PARAMETER                                    | CONDITIONS   | MIN. | MAX. | UNIT |
|-----------|--|--|------|------|------|
| $E_{RSM}$ | non-repetitive peak reverse avalanche energy | $L = 120 \text{ mH}$ ; $T_j = T_{j \text{ max}}$ prior to surge; inductive load switched off | –    | 10   | mJ   |
|           | BYG60D to J                                  |  |      | 7    | mJ   |
| $T_{stg}$ | storage temperature                          |  | –65  | +175 | °C   |
| $T_j$     | junction temperature                         | see Fig.4  | –65  | +175 | °C   |

### ELECTRICAL CHARACTERISTICS

$T_j = 25 \text{ °C}$  unless otherwise specified.

| SYMBOL      | PARAMETER                           | CONDITIONS  | MIN. | TYP. | MAX. | UNIT        |     |    |     |    |
|-------------|-------------------------------------|---|------|------|------|-------------|-----|----|-----|----|
| $V_F$       | forward voltage                     | $I_F = 1 \text{ A}$ ; $T_j = T_{j \text{ max}}$ ; see Fig.5   | –    | –    | 0.98 | V           |     |    |     |    |
|             |                                     | $I_F = 1 \text{ A}$ ; see Fig.5   | –    | –    | 1.20 | V           |     |    |     |    |
| $V_{(BR)R}$ | reverse avalanche breakdown voltage | $I_R = 0.1 \text{ mA}$  |      |      |      |             |     |    |     |    |
|             |                                     |   |      |      |      | BYG60D      | 300 | –  | –   | V  |
|             |                                     |   |      |      |      | BYG60G      | 500 | –  | –   | V  |
|             |                                     |   |      |      |      | BYG60J      | 700 | –  | –   | V  |
|             |                                     |   |      |      |      | BYG60K      | 900 | –  | –   | V  |
| BYG60M      | 1100                                | –   | –    | V    |      |             |     |    |     |    |
| $I_R$       | reverse current                     | $V_R = V_{RRMmax}$ ;<br>see Fig.6   | –    | –    | 5    | µA          |     |    |     |    |
|             |                                     | $V_R = V_{RRMmax}$ ; $T_j = 165 \text{ °C}$ ;<br>see Fig.6  | –    | –    | 100  | µA          |     |    |     |    |
| $t_{rr}$    | reverse recovery time               | when switched from $I_F = 0.5 \text{ A}$ to $I_R = 1 \text{ A}$ ; measured at $I_R = 0.25 \text{ A}$ ;<br>see Fig.8 |      |      |      |             |     |    |     |    |
|             |                                     |   |      |      |      | BYG60D to J | –   | –  | 250 | ns |
|             | BYG60K and M                        | –   | –    | 300  | ns   |             |     |    |     |    |
| $C_d$       | diode capacitance                   | $V_R = 0 \text{ V}$ ; $f = 1 \text{ MHz}$   |      |      |      |             |     |    |     |    |
|             |                                     |   |      |      |      | BYG60D to J | –   | 30 | –   | pF |
|             | BYG60K and M                        | –   | 25   | –    | pF   |             |     |    |     |    |

### THERMAL CHARACTERISTICS

| SYMBOL                | PARAMETER                                     | CONDITIONS | VALUE | UNIT |
|-----------------------|---|------------|-------|------|
| $R_{th \text{ j-tp}}$ | thermal resistance from junction to tie-point |            | 25    | K/W  |
| $R_{th \text{ j-a}}$  | thermal resistance from junction to ambient   | note 1     | 100   | K/W  |
|                       |   | note 2     | 150   | K/W  |

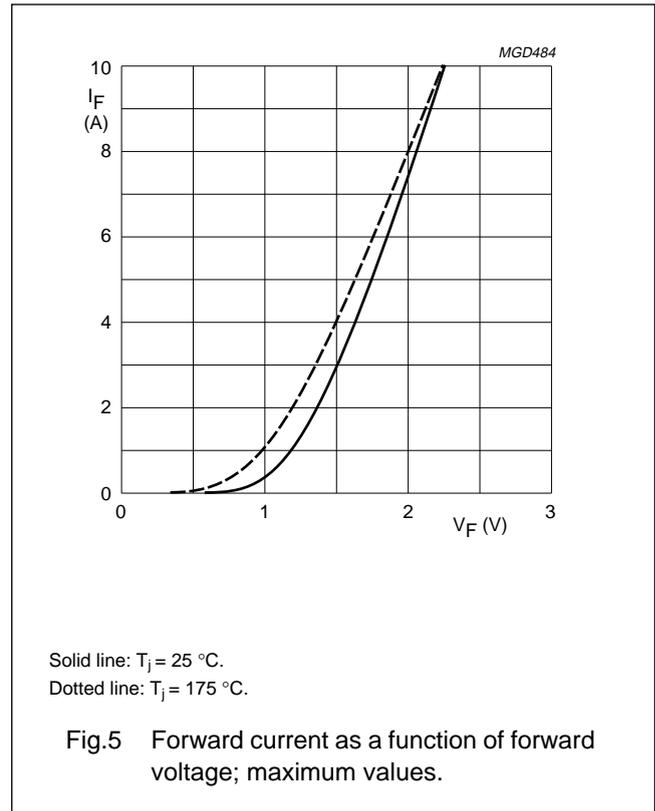
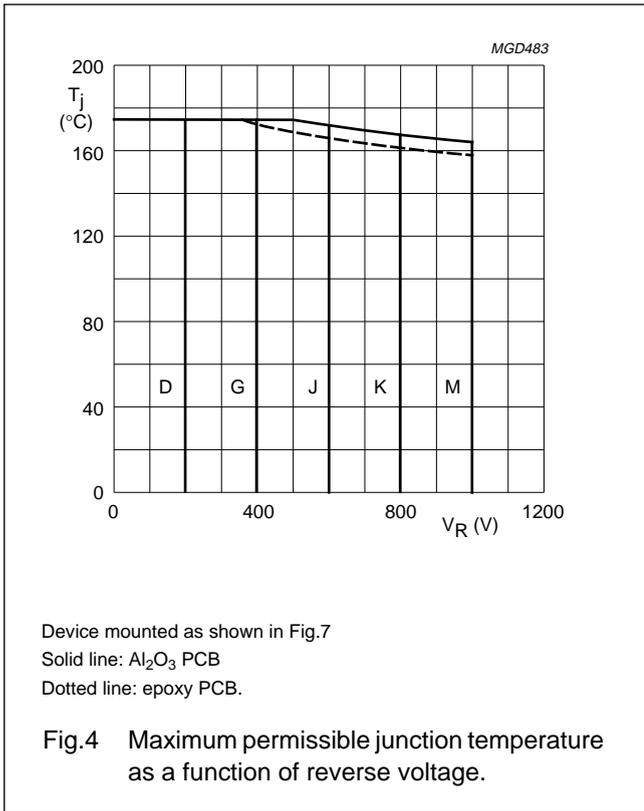
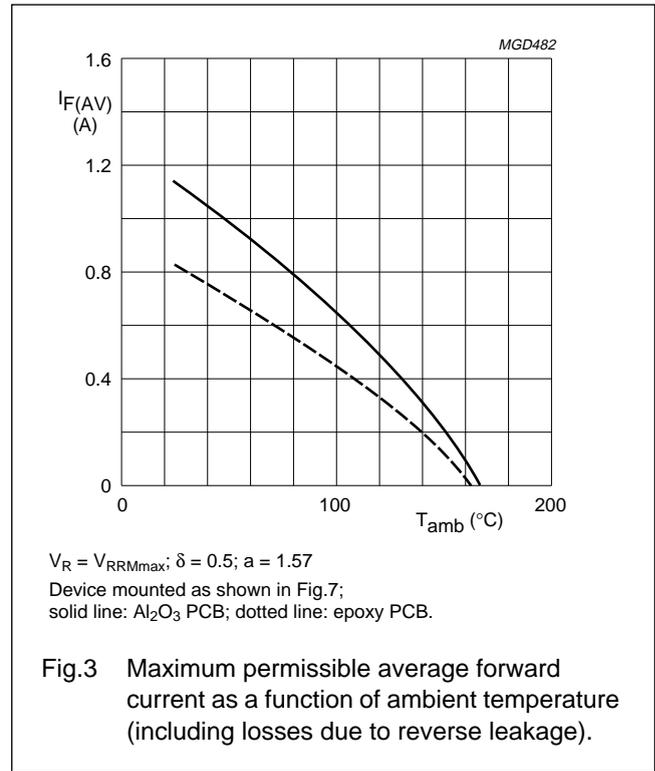
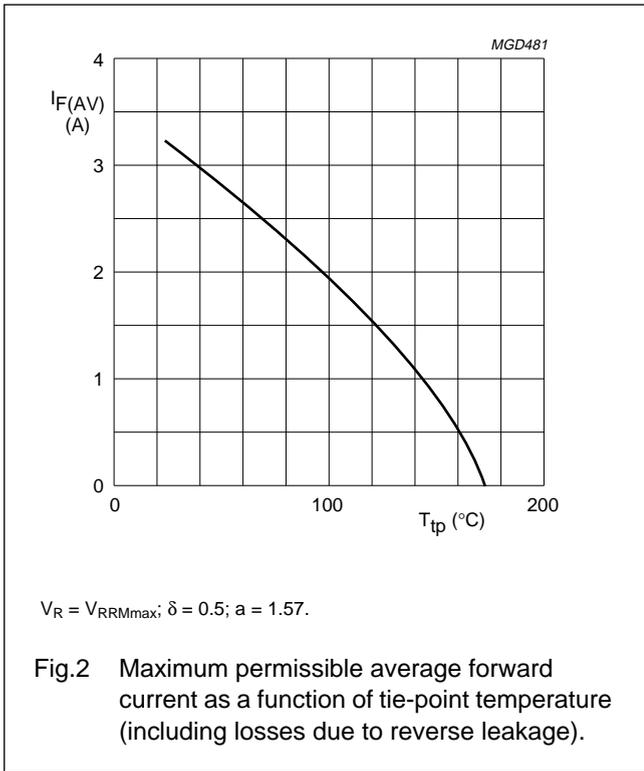
#### Notes

- Device mounted on  $\text{Al}_2\text{O}_3$  printed-circuit board, 0.7 mm thick; thickness of copper  $\geq 35 \text{ µm}$ , see Fig.7.
- Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper  $\geq 40 \text{ µm}$ , see Fig.7.  
For more information please refer to the 'General Part of Handbook SC01'.

Fast soft-recovery  
controlled avalanche rectifiers

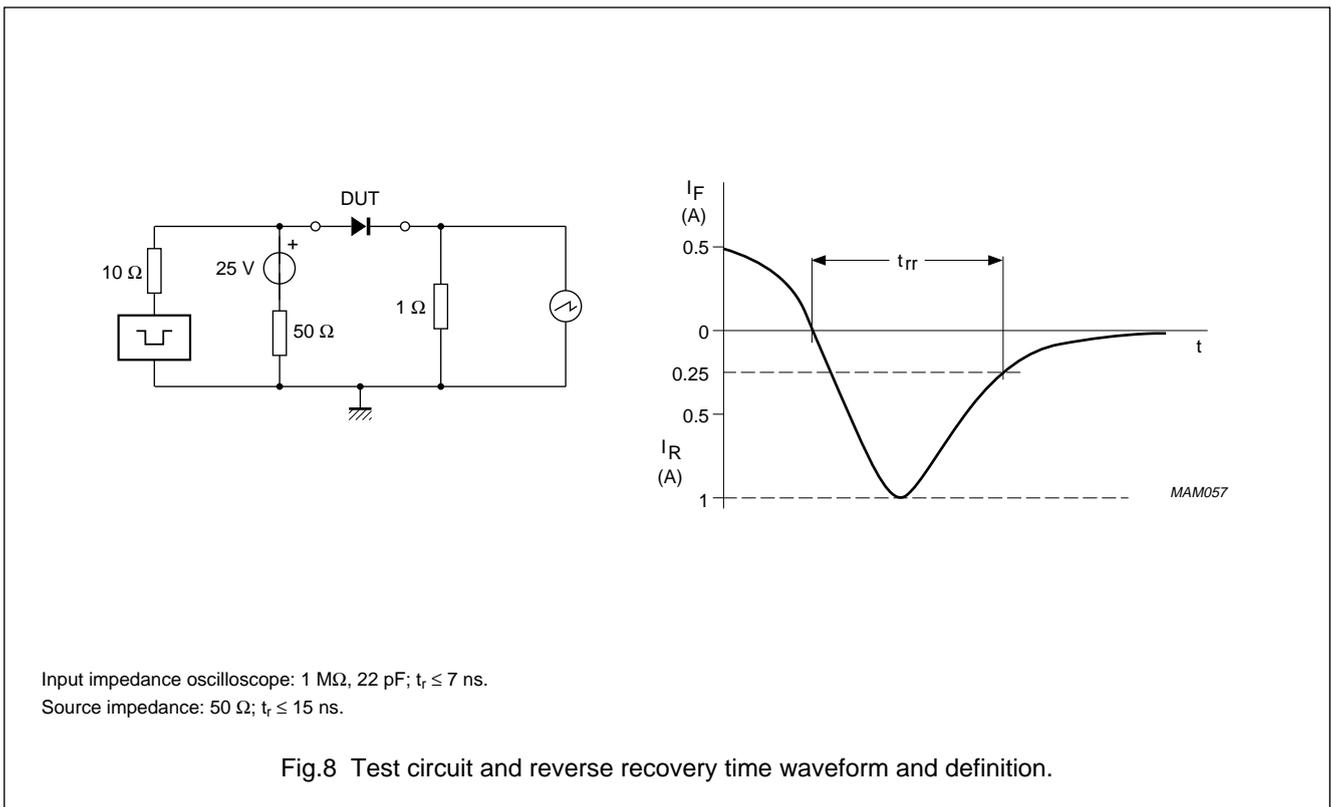
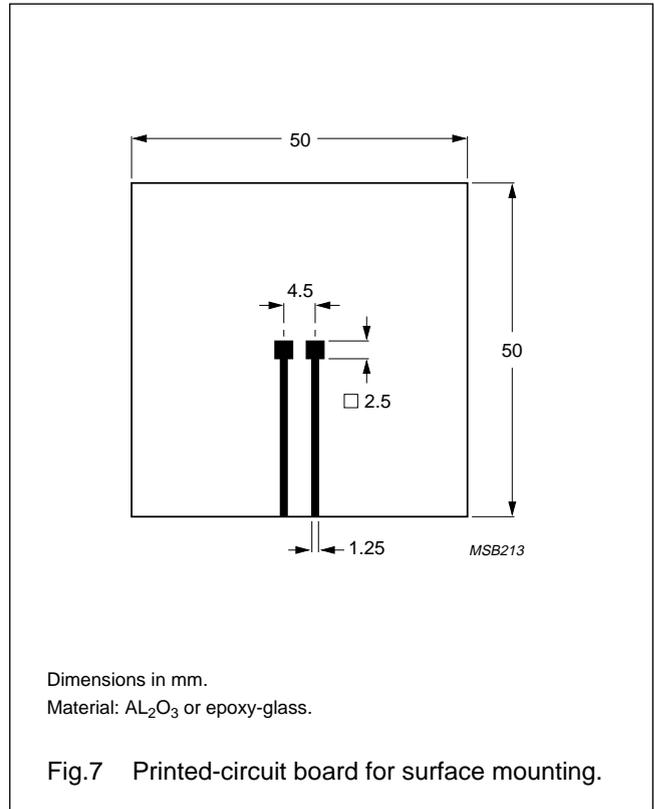
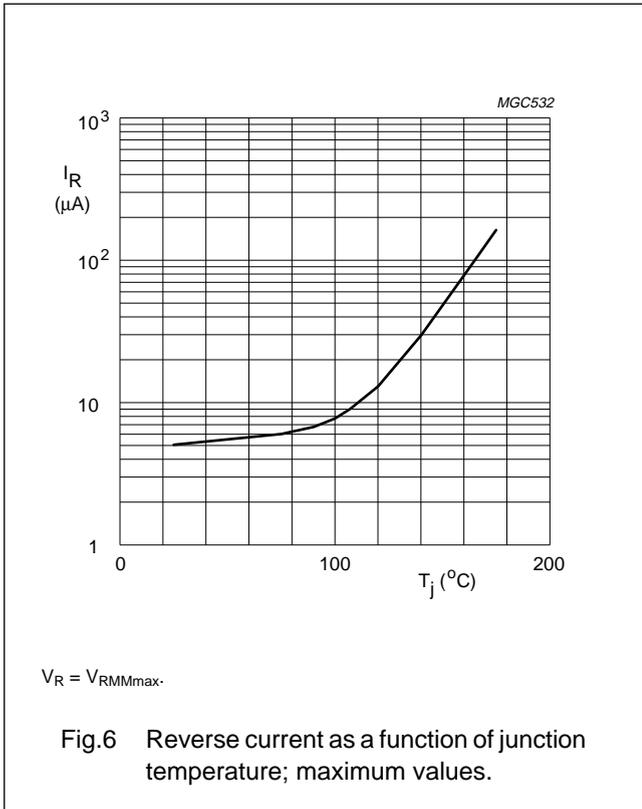
BYG60 series

GRAPHICAL DATA



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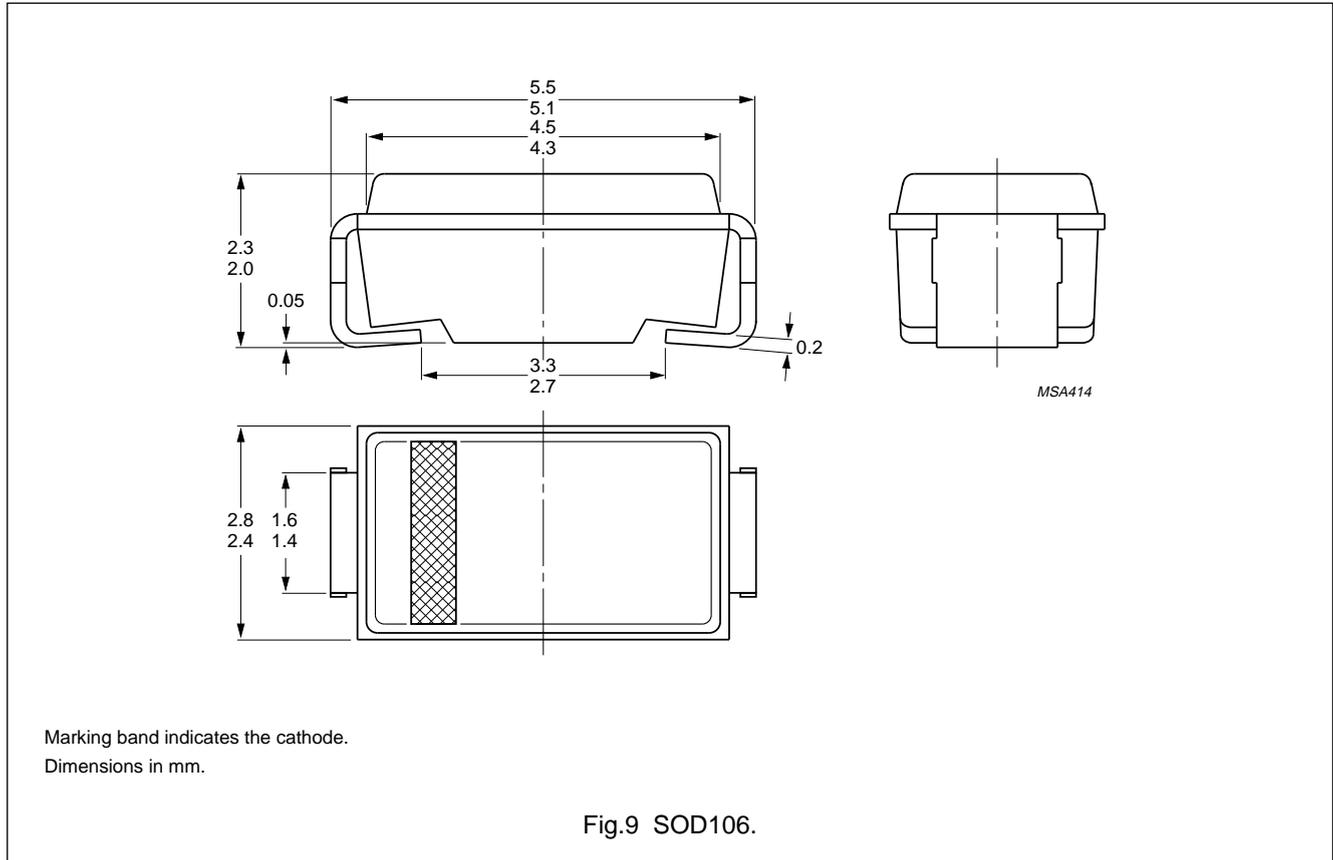
BYG60 series



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PACKAGE OUTLINE



DEFINITIONS

|   |   |
|---|---|
| <b>Data sheet status</b>  |   |
| Objective specification   | This data sheet contains target or goal specifications for product development.       |
| Preliminary specification   | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification   | This data sheet contains final product specifications.                                |
| <b>Limiting values</b>  |   |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. |   |
| <b>Application information</b>  |   |
| Where application information is given, it is advisory and does not form part of the specification.   |   |

LIFE SUPPORT APPLICATIONS

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